
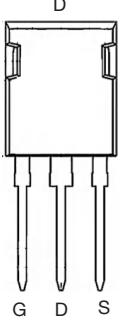




# TMG160P10HMP


# P-Channel Enhancement Mosfet

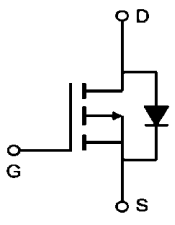
|  |  |   |
|--|--|---|
| <p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul> | <p><b>General Features</b></p> <p><math>V_{DS} = -100V</math> <math>I_D = -160A</math></p> <p><math>R_{DS(ON)} = 6 m\Omega (typ.) @ V_{GS} = -10V</math></p> <p>100% UIS Tested<br/>100% <math>R_g</math> Tested</p> |  |
|--|--|---|



MP:TO-247-3L

Marking: G160P10H





**Absolute Maximum Ratings:** ( $T_c = 25^\circ C$  unless otherwise noted)

| Symbol         | Parameter  | Ratings     | Units      |
|----------------|--|-------------|------------|
| $V_{DS}$       | Drain-Source Voltage                             | -100        | V          |
| $V_{GS}$       | Gate-Source Voltage                              | $\pm 20$    | V          |
| $I_D$          | Continuous Drain Current- $T_c = 25^\circ C$     | -160        | A          |
|                | Continuous Drain Current- $T_c = 100^\circ C$    | -94         |            |
| $I_{DM}$       | Pulsed Drain Current                             | -600        |            |
| EAS            | Single Pulse Avalanche Energy                    | 1232        | mJ         |
| $P_D$          | Power Dissipation                                | 305         | W          |
| $T_j, T_{STG}$ | Operating and Storage Junction Temperature Range | -55 to +175 | $^\circ C$ |

**Thermal Characteristics:**

| Symbol          | Parameter                               | Max | Units        |
|-----------------|---|-----|--------------|
| $R_{\theta Jc}$ | Thermal Resistance, Junction to Case    | 0.4 | $^\circ C/W$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 62  |              |



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**Electrical Characteristics** (  $T_J=25$  unless otherwise specified ) :

| Symbol                       | Parameter                            | Conditions                                 | Min. | Typ.  | Max.      | Unit           |
|------------------------------|--------------------------------------|--|------|-------|-----------|----------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage       | $V_{GS}=0V, I_D=-250\mu A$                 | -100 | ---   | ---       | V              |
| $\Delta BV_{DSS}/\Delta T_J$ | $BV_{DSS}$ Temperature Coefficient   | Reference to $25^\circ C, I_D=1mA$         | ---  | ---   | ---       | V/ $^\circ C$  |
| $R_{DS(ON)}$                 | Static Drain-Source On-Resistance    | $V_{GS}=-10V, I_D=-22A$                    | ---  | 6     | 8         | m $\Omega$     |
|                              |                                      | $V_{GS}=-4.5V, I_D=-22A$                   | ---  | ---   | ---       |                |
| $V_{GS(th)}$                 | Gate Threshold Voltage               | $V_{GS}=V_{DS}, I_D=-250\mu A$             | -3   | -3.5  | -4        | V              |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient |  | ---  | ---   | ---       | mV/ $^\circ C$ |
| $I_{DSS}$                    | Drain-Source Leakage Current         | $V_{DS}=-100V, V_{GS}=0V, T_J=25^\circ C$  | ---  | ---   | 1         | $\mu A$        |
|                              |                                      | $V_{DS}=-100V, V_{GS}=0V, T_J=100^\circ C$ | ---  | ---   | ---       |                |
| $I_{GSS}$                    | Gate-Source Leakage Current          | $V_{GS}=\pm 20V, V_{DS}=0V$                | ---  | ---   | $\pm 100$ | nA             |
| $g_{fs}$                     | Forward Transconductance             | $V_{DS}=-10V, I_D=-5A$                     | ---  | ---   | ---       | S              |
| $R_g$                        | Gate Resistance                      | $V_{DS}=0V, V_{GS}=0V, f=1MHz$             | ---  | 1.7   | ---       | $\Omega$       |
| $Q_g$                        | Total Gate Charge                    |  | ---  | 170   | ---       | nC             |
| $Q_{gs}$                     | Gate-Source Charge                   | $V_{DS}=-50V, V_{GS}=-10V, I_D=-5A$        | ---  | 45    | ---       |                |
| $Q_{gd}$                     | Gate-Drain Charge                    |  | ---  | 31    | ---       |                |
| $T_{d(on)}$                  | Turn-On Delay Time                   |  | ---  | 15    | ---       | ns             |
| $T_r$                        | Rise Time                            | $V_{GS}=-10V,$                             | ---  | 35    | ---       |                |
| $T_{d(off)}$                 | Turn-Off Delay Time                  | $V_{DS}=-50V, I_D=-22A,$                   | ---  | 100   | ---       |                |
| $T_f$                        | Fall Time                            | $R_G=1\Omega$                              | ---  | 35    | ---       |                |
| $C_{iss}$                    | Input Capacitance                    |  | ---  | 11687 | ---       | pF             |
| $C_{oss}$                    | Output Capacitance                   | $V_{DS}=-50V, V_{GS}=0V, f=1MHz$           | ---  | 998   | ---       |                |
| $C_{rss}$                    | Reverse Transfer Capacitance         |  | ---  | 139   | ---       |                |

**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                            | Min. | Typ. | Max. | Unit |
|----------|--|---------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,4</sup> | $V_G=V_D=0V, \text{Force Current}$    | ---  | ---  | -160 | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V, I_S=-22A, T_J=25^\circ C$ | ---  | ---  | -1.2 | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=-22A, di/dt=100A/\mu s,$         | ---  | 86   | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  | $T_J=25^\circ C$                      | ---  | 271  | ---  | nC   |

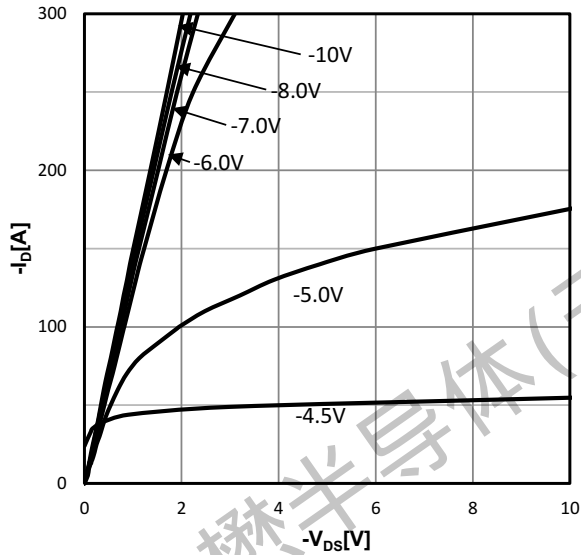


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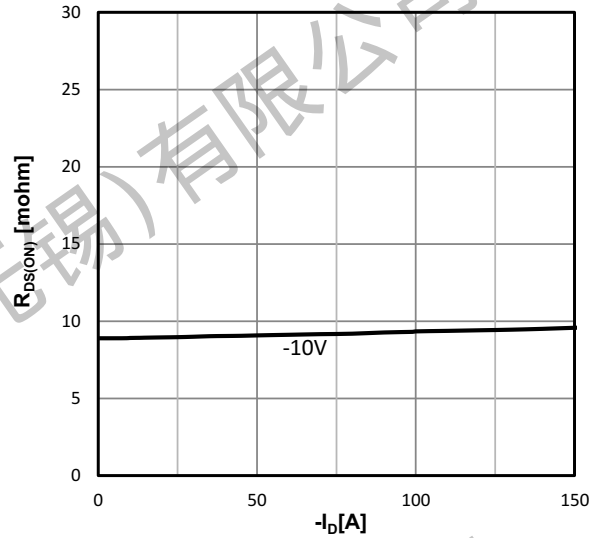
Characteristics Curve:

Figure 1: Typ. output characteristics



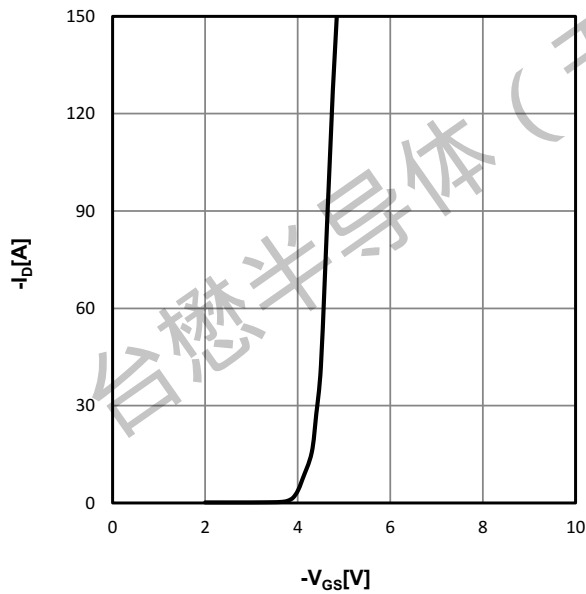
$I_D = f(V_{DS}), T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$

Figure 2: Typ. drain-source on resistance



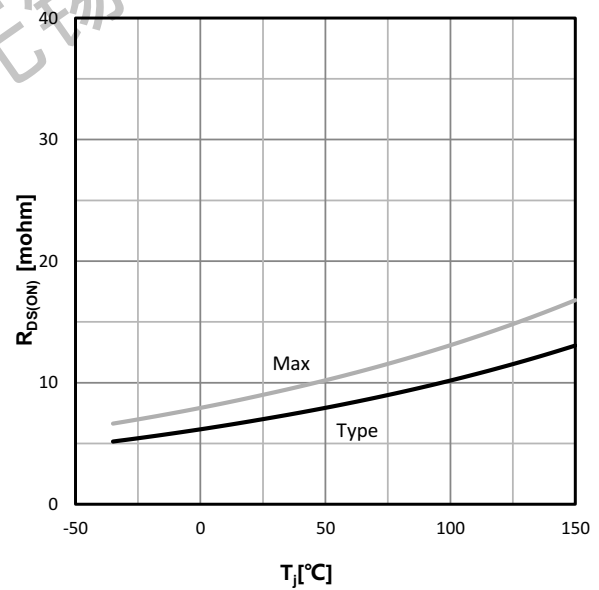
$R_{DS(on)} = f(I_D), T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$

Figure 3: Typ. transfer characteristics



$I_D = f(V_{GS}), |V_{DS}| > 2|I_D|R_{DS(on)max};$

Figure 4: drain-source on resistance



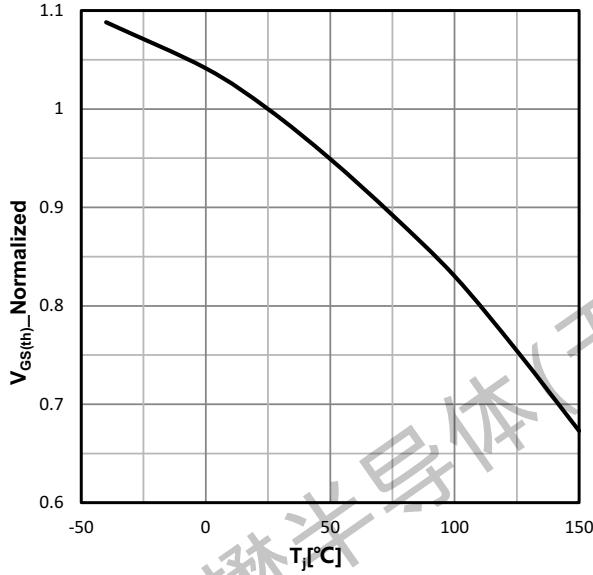
$R_{DS(on)} = f(T_j), I_D = -20\text{A}, V_{GS} = -10\text{V};$



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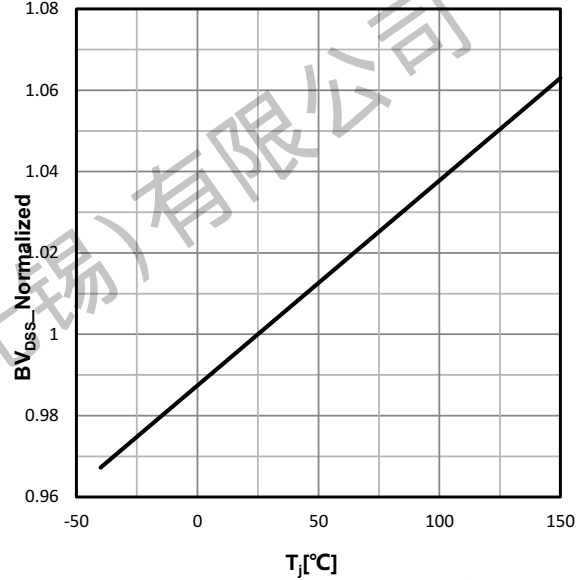
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Figure 5: Typ. gate threshold voltage



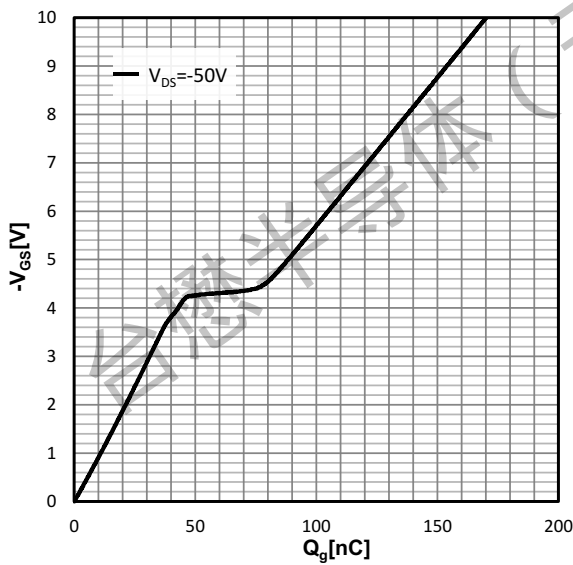
$V_{GS} = f(T_j)$ ,  $V_{GS} = V_{DS}$ ,  $I_D = -250\mu\text{A}$ ;

Figure 6: Drain-source breakdown voltage



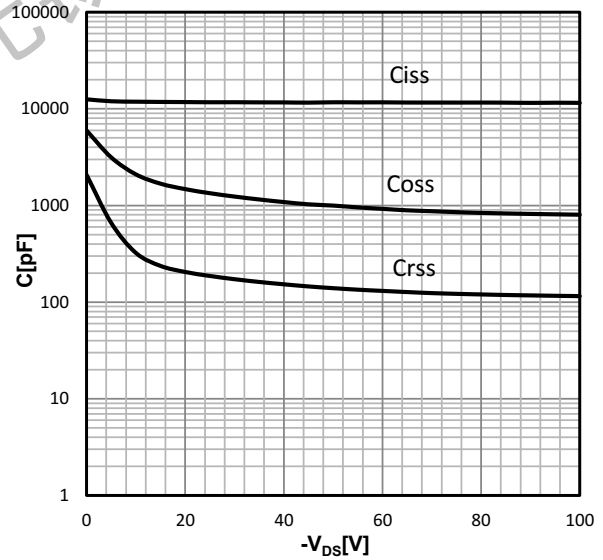
$V_{BR(DSS)} = f(T_j)$ ;  $I_D = -250\mu\text{A}$ ;

Figure 7: Typ. gate charge



$V_{GS} = f(Q_g)$ ,  $I_D = -20\text{A}$ ,  $T_j = 25^{\circ}\text{C}$ ; parameter:  $V_{DS}$

Figure 8: Typ. Capacitances



$C = f(V_{DS})$ ;  $V_{GS} = 0\text{V}$ ;  $f = 1.0\text{ MHz}$ ;



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Figure 9: Power dissipation

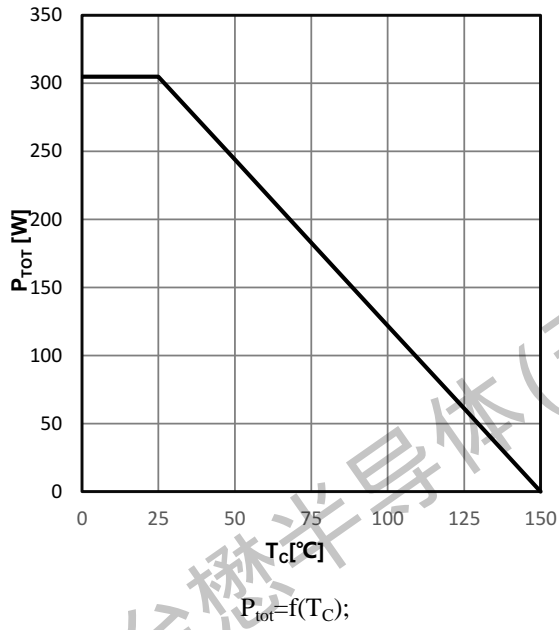


Figure 10: Drain current

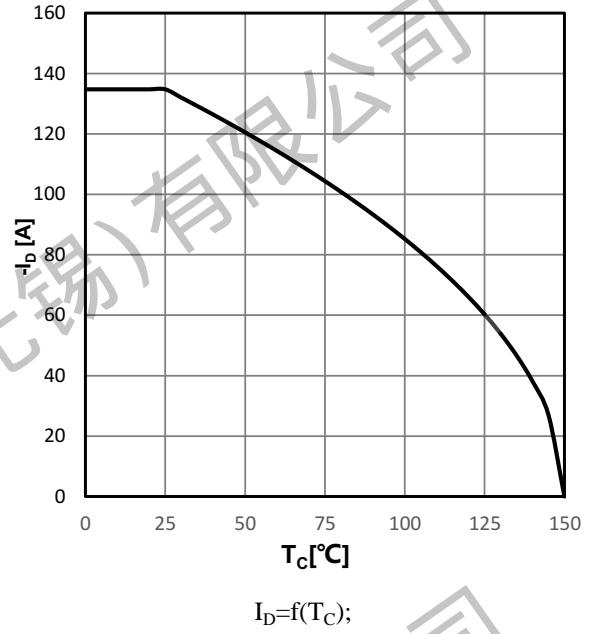
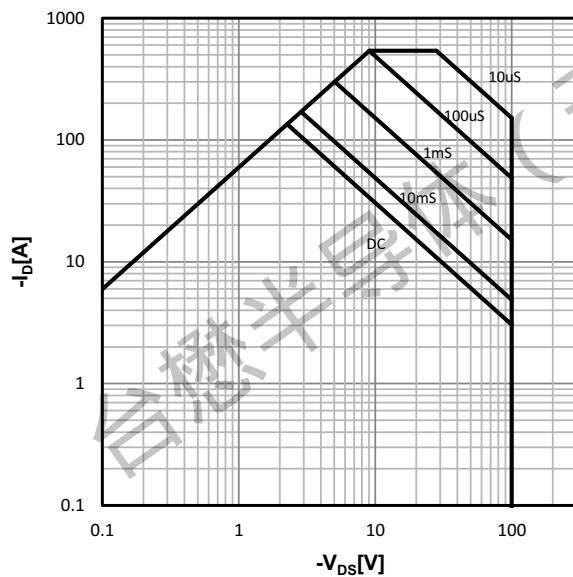
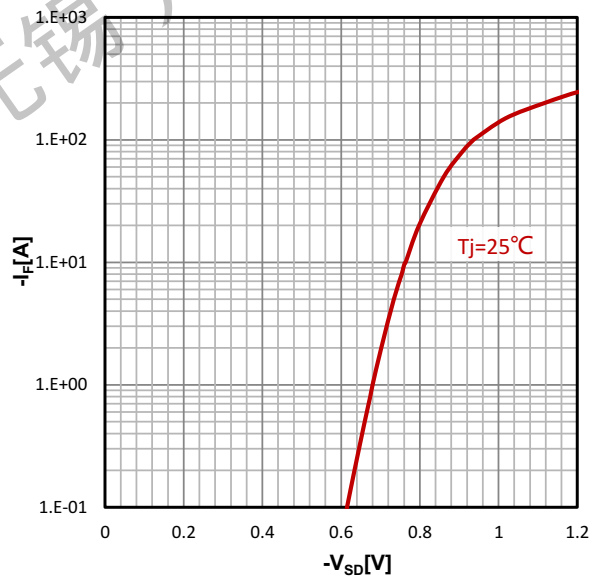


Figure 11: Safe operating area



$I_D=f(V_{DS})$ ;  $T_C=25\text{ }^\circ\text{C}$ ;  $D=0$ ; parameter: tp

Figure 12: Typ. forward characteristics

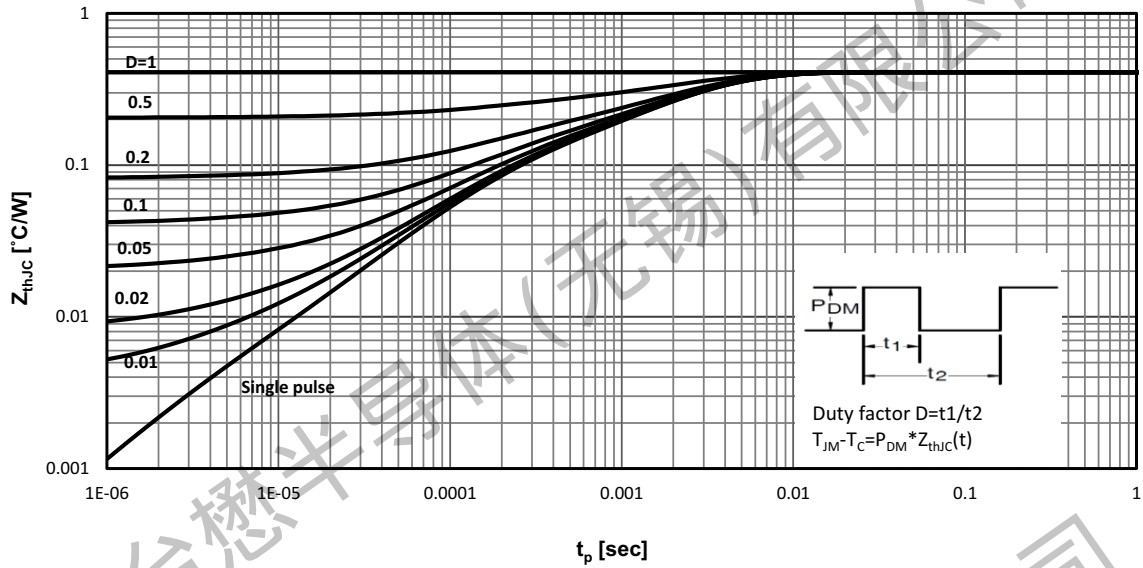


$I_F=f(V_{SD})$

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Figure 13: Max. Transient Thermal Impedance



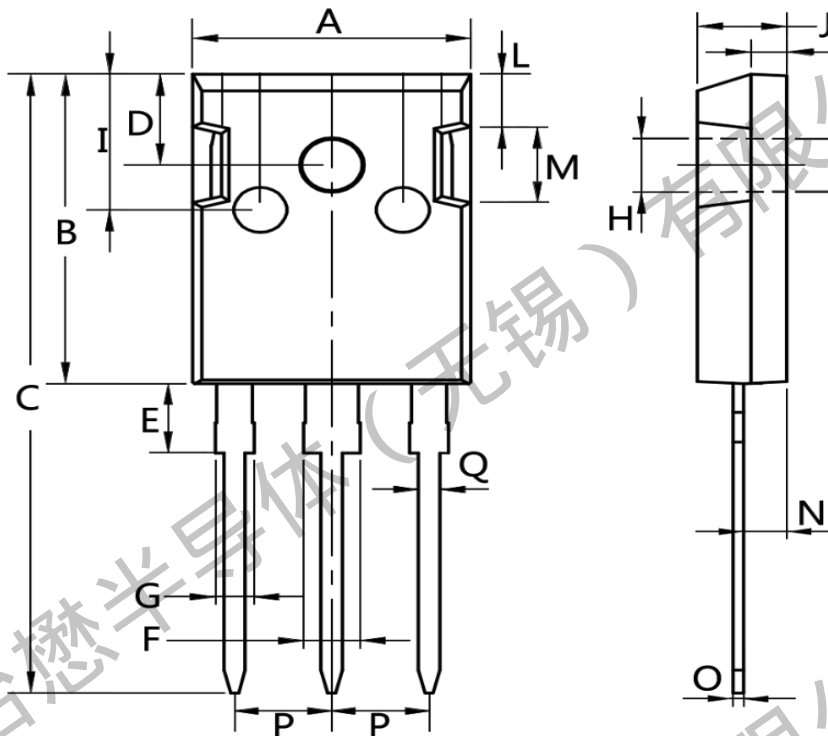
$Z_{thJC} = f(t_p)$ ; parameter: D



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Package Mechanical Data :TO-247-3L

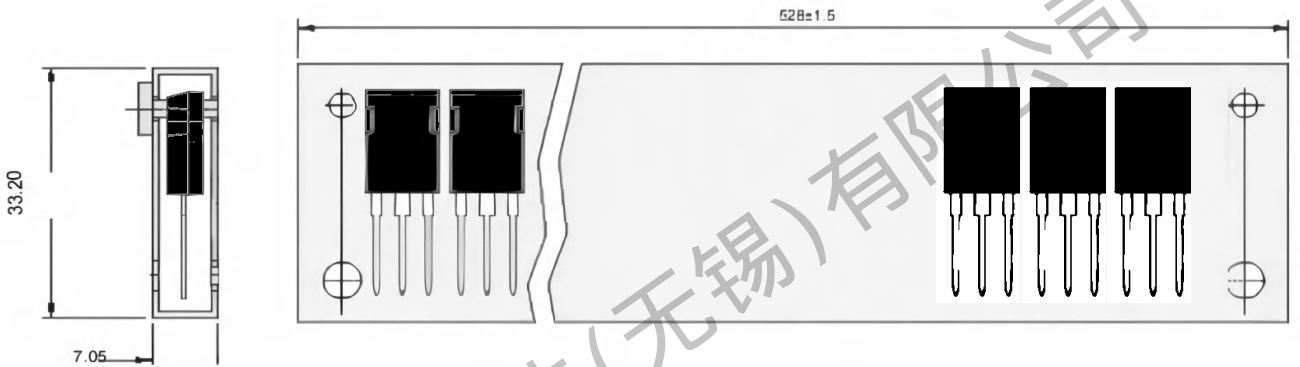


| Dim. | Min.     | Max. |
|------|----------|------|
| A    | 15.0     | 16.0 |
| B    | 20.0     | 21.0 |
| C    | 41.0     | 42.0 |
| D    | 5.0      | 6.0  |
| E    | 4.0      | 5.0  |
| F    | 2.5      | 3.5  |
| G    | 1.75     | 2.5  |
| H    | 3.0      | 3.5  |
| I    | 8.0      | 10.0 |
| J    | 4.9      | 5.1  |
| K    | 1.9      | 2.1  |
| L    | 3.5      | 4.0  |
| M    | 4.75     | 5.25 |
| N    | 2.0      | 3.0  |
| O    | 0.55     | 0.75 |
| P    | Typ 5.08 |      |
| Q    | 1.2      | 1.3  |



**TMG160P10HMP**

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All Dimensions are in mm

**1.TO-247-3L Packaging**

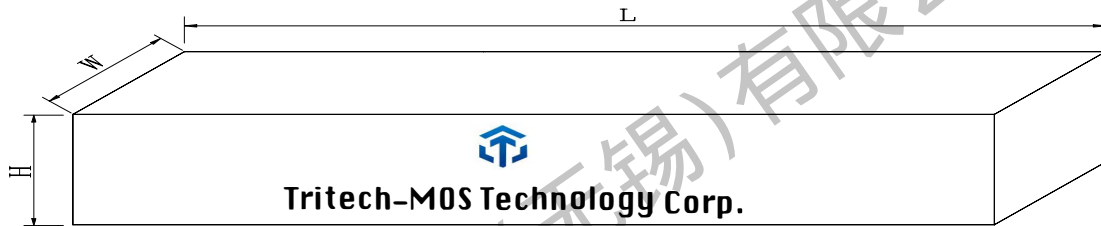
| Package   | Packing Form | Quantity |                  |               |
|-----------|--------------|----------|------------------|---------------|
|           |              | Tube     | Inner Box [kpcs] | Outbox [kpcs] |
| TO-247-3L | Tube Tape    | 30       | 5                | 1             |



# TMG160P10HMP

# P-Channel Enhancement Mosfet

## Inner Box



Dimension : 580 (L)×154(W) ×49(H) mm

Quantity : 30 ×15Ea = 450pcs Or 30 ×20Ea = 600pcs

## Outer Box



Dimension : 595(L)×285(W) ×185(H) mm

Quantity : 450×5Ea = 2250pcs Or 600 ×5Ea = 3000pcs



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Revision history:

| Date       | Rev   | Description | Page |
|------------|-------|-------------|------|
| 2023.08.01 | 23.08 | Original    |      |